



Product Summary

BV _{DSS}	Rds(on) max	I⊳ max
	42mΩ @ V _{GS} = 10V	4.6A
40V	52mΩ @ V _{GS} = 4.5V	4.1A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

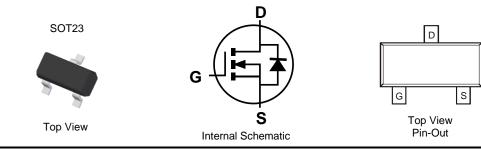
N-CHANNEL ENHANCEMENT MODE MOSFET

- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMN4035LQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 🚯
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMN4035LQ-7	SOT23	3000/Tape & Reel
DMN4035LQ-13	SOT23	10000/Tape & Reel

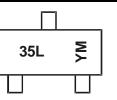
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



35L = Product Type Marking Code YM = Date Code Marking

Y = Year (ex: G = 2019)

M = Month (ex: 9 = September)

Date Code Key

	Date Code Rey												
	Year	2019	20	20	2021	2022	20	23	2024	2025	20	26	2027
	Code	G	ŀ	-		J	ł	<	L	М		N	0
ĺ	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage		Vdss	40	V	
Gate-Source Voltage		V _{GSS}	±20	V	
Continuous Drain Current (Note 6) V_{GS} = 10V	Steady State	T _A = +25°C T _A = +70°C	ID	4.6 3.7	A
Maximum Body Diode Forward Current (Note 6)		ls	1.5	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	Idм	25	А		
Pulsed Source Current (10µs Pulse, Duty Cycle = 19	%)		lsм	25	А

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Power Dissipation (Note 5)		PD	0.72	W
Thermal Resistance, Junction to Ambient (Note 5) Steady State		Reja	171	°C/W
Power Dissipation (Note 6)		PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	93	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	۵°

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	1 - 1						
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current	IDSS	_	—	1	μA	V _{DS} = 40V, V _{GS} = 0V	
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)			•	•			
Gate Threshold Voltage	V _{GS(TH)}	1	—	3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	Descent	_	30	42	mΩ	VGS = 10V, ID = 4.3A	
	Rds(on)	_	40	52	11122	V _{GS} = 4.5V, I _D = 3.9A	
Diode Forward Voltage	V _{SD}	_	0.7	1.1	V	V _{GS} = 0V, I _S = 1.25A	
DYNAMIC CHARACTERISTICS (Note 8)			•	•			
Input Capacitance	Ciss	_	574	_		$V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz	
Output Capacitance	Coss	_	87.8	—	pF		
Reverse Transfer Capacitance	Crss	_	38.7	_			
Gate Resistance	Rg	_	1.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.9	_			
Total Gate Charge (V _{GS} = 10V)	Qg	_	12.5	_	nC		
Gate-Source Charge	Q _{gs}	_	1.7	_	nc	$V_{DS} = 20V, I_D = 3.9A$	
Gate-Drain Charge	Qgd	_	2.2	_			
Turn-On Delay Time	td(on)	_	3.1	_			
Turn-On Rise Time	tR	_	2.6	_	1	$V_{DD} = 20V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	15	_	ns	$R_L = 20\Omega, R_G = 6\Omega$	
Turn-Off Fall Time	tF	_	5.5	_	1		
Reverse Recovery Time	trr	_	6.5	_	ns		
Reverse Recovery Charge	Q _{RR}	_	1.2	_	nC	— I _F = 3.9A, di/dt = 500A/μs	

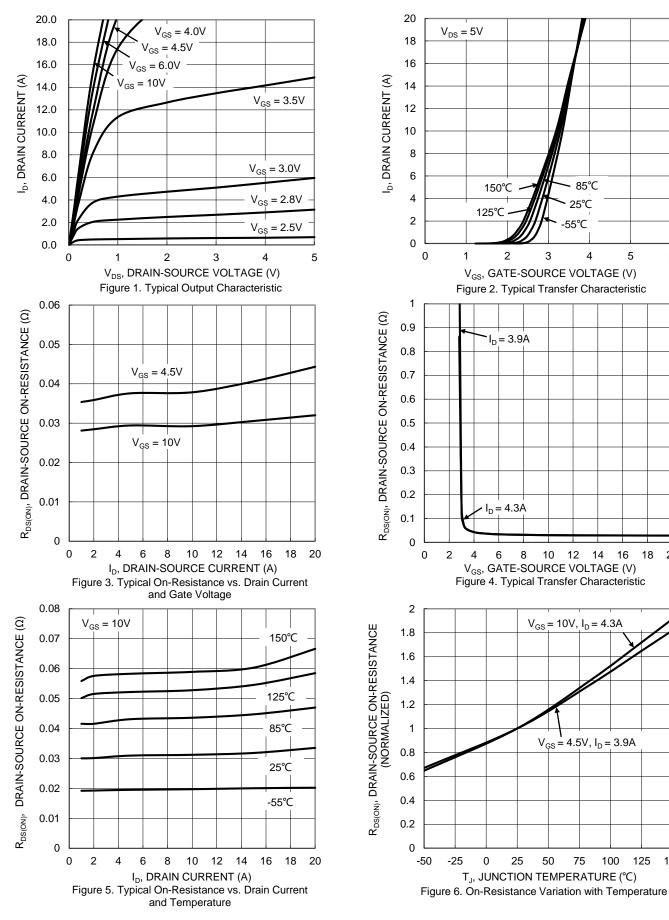
Notes:

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.



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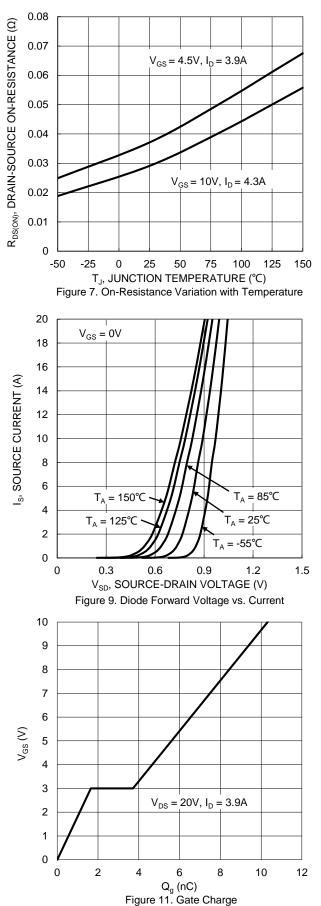
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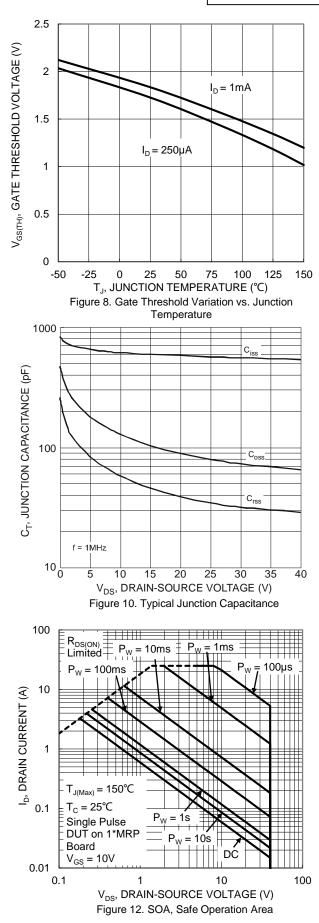


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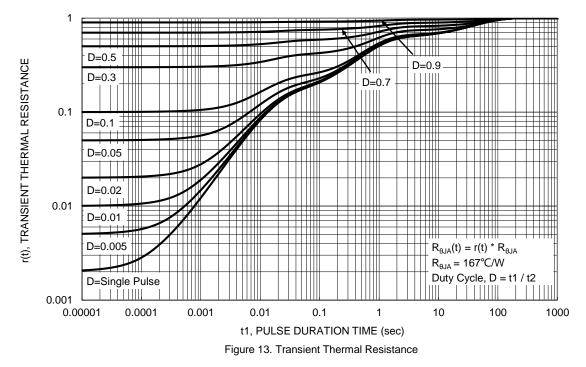






DMN4035LQ Document number: DS41026 Rev. 3 - 2

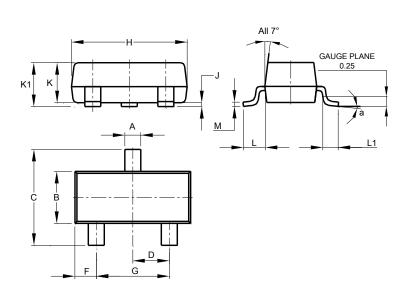






Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



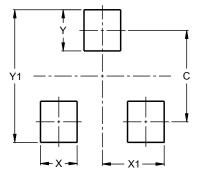
	SOT23							
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Н	2.80	3.00	2.90					
J	0.013	0.10	0.05					
K	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
М	0.085	0.150	0.110					
а	0°	8°						
All	All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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